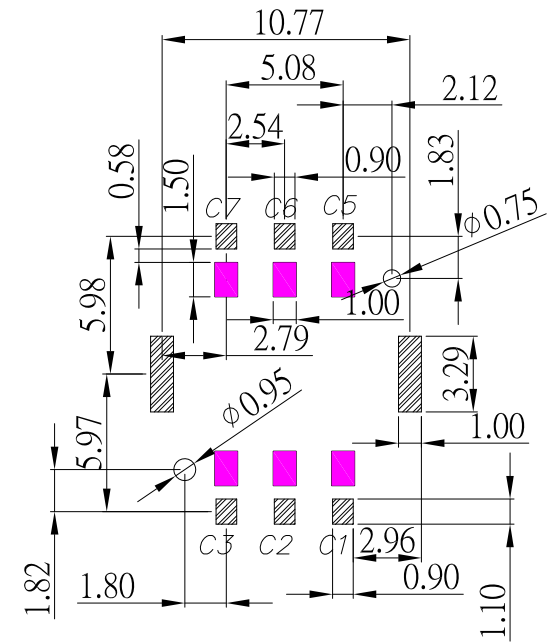
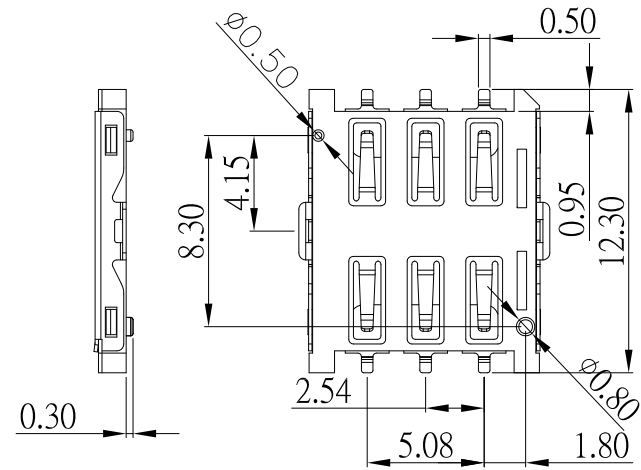
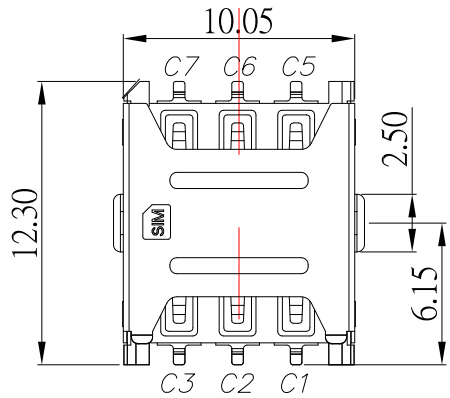
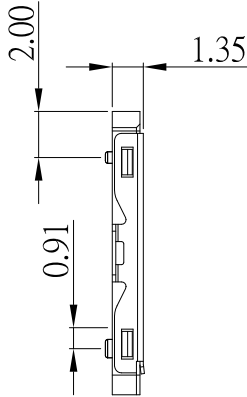
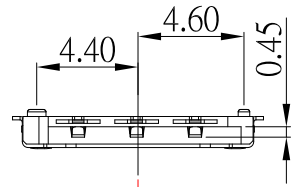
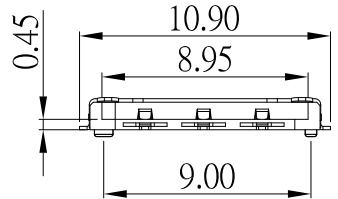
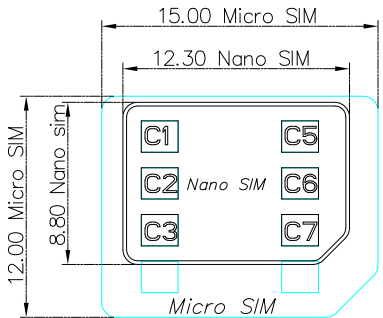


SIM pin assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



PCB通空位置  
 RECOMMENDED PCB LAYOUT

P.C.B LAYOUT MOUNTING PATTERN



MATERIALS:

- HOUSING : HIGH TEMPERATURE THERMOPLASTIC
- CONTACT : PHOSPHOR BRONZE
- SHELL : SUS

Finish:

- Finish: CONTACT: PLATED GOLD IN MATING AREA ;  
GOLD PLATED ON SOLDER BALLS ;  
NICKEL UNDER PLATED OVERALL
- SHELL: NICKEL UNDER PLATED SURFACE LAYER

SPECIFICATION:

- CURRENT RATING : 0.5 mA AC / DC MAX.
- VOLTAGE RATING : 125V AC / DC
- INSULATION RESISTANCE : 1000M $\Omega$  MIN.
- CONTACT RESISTANCE : 100m $\Omega$  MAX.
- OPERATING TEMPERATURE RANGE : -40°C TO +85°C.
- STORAGE TEMPERATURE RANGE : -40°C TO +85°C.

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TOLERANCE UNLESS OTHERWISE STATED :  
 Up to 5 ±0.2  
 Above 5 ~ 15 ±0.3  
 Above 15 ~ 30 ±0.4  
 Above 30 ~ 50 ±0.5  
 Angle ±0.3

3RD. ANGEL'S



UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	02/01/23			
CHECKED BY:	DATE	FINISH	MODLE	Nano SIM CARD NO PUSH 1.35H 有柱
Jacky Chen	02/01/23			
APPROVED BY:	DATE	SCALE	DWG NO.	SIZE
Tony Kao	02/01/23	1 : 1	NSIM-0201G06A-S267	A4
		SHEET NO.	PART NO.	VER
		1 of 1	NSIM-0201G06A-S267	R2

ITEM NO.	DESCRIPTION	DRAWN	DATE
2	修正尺寸標示	Jack	020123
1	更新OPERATING TEMPERATURE RANGE	Jack	101221